Material Declaration Report

Package Type:	SOT89-3
Pericom Package Code:	TD03 (Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	45.278
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	30
Reflow Cycles:	3
Rev Date:	Mar.05.2009

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	19.200	J	Silica Fused	60676-86-0	70.90	13.61280
			Epoxy Resin	29690-82-2	12.50	2.40000
			Phenolic Resin	9003-35-4	8.50	1.63200
			Brominated Resin	Secret	1.50	0.28800
			Carbon Black	1333-86-4	0.55	0.10560
			Wax	Secret	1.25	0.24000
			Flame Retardant	Secret	3.00	0.57600
			Catalyst	Secret	0.50	0.09600
			Stress Absorbent	Secret	0.30	0.05760
			Coupling Agent	Secret	0.50	0.09600
			Releasing Agent.	Secret	0.50	0.09600
LEAD FRAME	25.000		Iron	7439-89-6	0.08	0.02000
			Phosphorus	7723-14-0	0.06	0.01500
			Copper	7440-50-8	99.86	24.96500
			Silver	7740-22-4	--	--
TERMINATION PLATING	0.275		Tin	7440-31-5	99.90	0.27473
			Impurity	Proprietary	0.10	0.00028
SILICON DIE	0.350		Silicon	7440-21-3	99.763	0.34917
			Aluminum(Al)	7429-90-5	0.200	0.00070
			Copper(Cu)	7440-50-8	0.001	0.00000
			Titanium(Ti)	7440-32-6	0.028	0.00010
			Phosphorus(P)	7664-38-2	0.003	0.00001
			Boron(B)	7440-42-8	0.005	0.00002
DIE ATTACH EPOXY	0.400		Silicon Dioxide	14464-46-1	46.25	0.18500
			Epoxy resin	29690-82-2	46.25	0.18500
			Curing Agent and Hardener	N/A	7.50	0.03000
GOLD WIRE	0.053		Au	7440-57-5	99.99	0.05299
			Other materials	Proprietary	0.01	0.00001

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Device	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<2	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb <1000ppm	Hg <1000ppm	Cr+6 <1000ppm	Cd <100ppm	PBB <1000ppm	PBDE <1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.